

## < GaN HEMT for satellite communication (SATCOM) earth station>

## MGFK50G3745

Ku band internally matched power GaN HEMT 13.75 - 14.5 GHz BAND / 100W

#### **DESCRIPTION**

The MGFK50G3745, GaN HEMT with an N-channel schottky gate, is designed for Ku-band applications.

#### **FEATURES**

• High voltage operation : VDS=24V

High output power
High efficiency
Po=50dBm (TYP.) @Pin=45dBm
PAE=30% (TYP.) @Pin=45dBm

• Designed for use in Class AB linear amplifiers

#### **APPLICATION**

• Amplifier for Ku-band SATCOM

#### **QUALITY**

• General & Industrial

#### **Packaging**

Individual case

#### RECOMMENDED BIAS CONDITIONS

• Vds=24V • Ids=2.4A • Rg= $10\Omega$ 

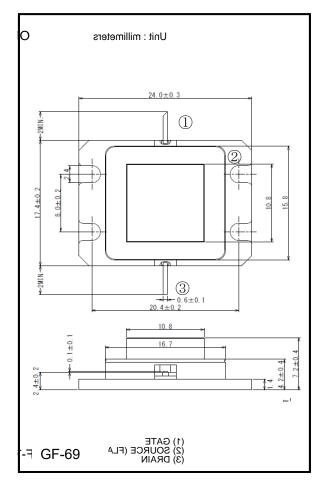
## Absolute maximum ratings (Ta=25°C)

Symbol	Parameter Ratings			
Vgso	Gate to Source Voltage	-10 V		
Vds	Orain to source voltage at Operating 27			
IGF	Forward gate current 160			
IGR	Reverse gate current -48		mA	
PT*1	Total power dissipation	375	W	
Pin	Input power	47	dBm	
Tch	Channel temperature	250	°C	
Tstg	Storage temperature	-55 to +125	°C	
1.70-2500				

<sup>\*1:</sup>Tc=25°C

## **Recommended operating Condition**

Symbol	Parameter	Limit	Unit
Tc	Maximum case operating temperature	85	လူ
Vds	Drain to source voltage	24	V
IDQ	Drain current without RF drive	2.4	Α



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#### **Electrical characteristics** (Ta=25°C)

Parameter	Symbol	Symbol Test conditions Limits			Unit	
			Min.	Тур.	Max.	
Gate to source cut-off voltage	VGS(off)	VDS=24V,ID=48mA	-1	-	-5	V
Output Power	Pout *2	VDS=24V,ID(RF off)=2.4A	49.0	50	-	dBm
Power added efficiency	PAE *2	f=13.75 – 14.5GHz *2 : Pin=45dBm *3 : Pin=25dBm	-	30	-	%
Linear power gain	GLP *3		8	10	1	dB
3 <sup>rd</sup> Order Intermodulation	IM3 *4	*4 : Two-tone Test,Po=41dBm	-	-25	-	dBc
distortion		(Single Carrier Level) Δ f=5MHz(IM3)				
Thermal resistance	Dtb(ob o) *5	A \ /6 44		0.4	0.6	°C/W
Thermal resistance	Rth(ch-c) *5	∆ Vf method	-	0.4	0.6	C/VV

<sup>\*5 :</sup>Channel-case

Specifications are subject to change without notice

ESD *6	Class 0	-199~

<sup>\*6 :</sup>Based on EIAJ ED-4701 C-111A(C=100pF,R=1.5kΩ)

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## 1. Po / GLP / PAE / IDRF vs. freq

## (Temperature Dependence @ IDQ=2.4A)

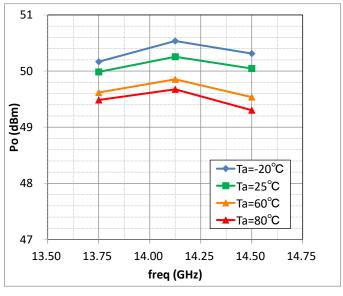


Fig.1-1 Po@Pin=45dBm vs. Freq.

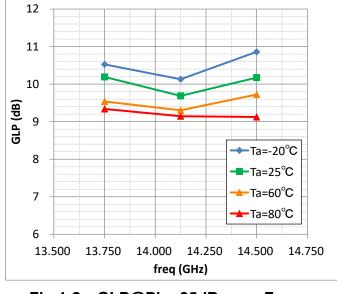


Fig.1-2 GLP@Pin=25dBm vs. Freq.

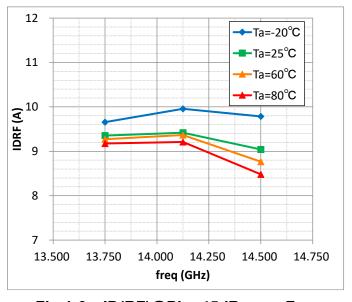


Fig.1-3 ID(RF)@Pin=45dBm vs. Freq.

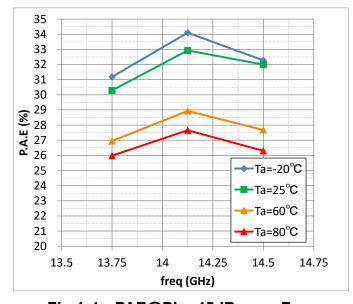


Fig.1-4 PAE@Pin=45dBm vs. Freq.

Measurement Condition: VDS=24 V, Idq=2.4A Rg=10Ω

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# 2. Pin – Pout / Gain / PAE / IDRF / IGRF Characteristics (VDS=24V, Idq=2.4A, Rg=10Ω)

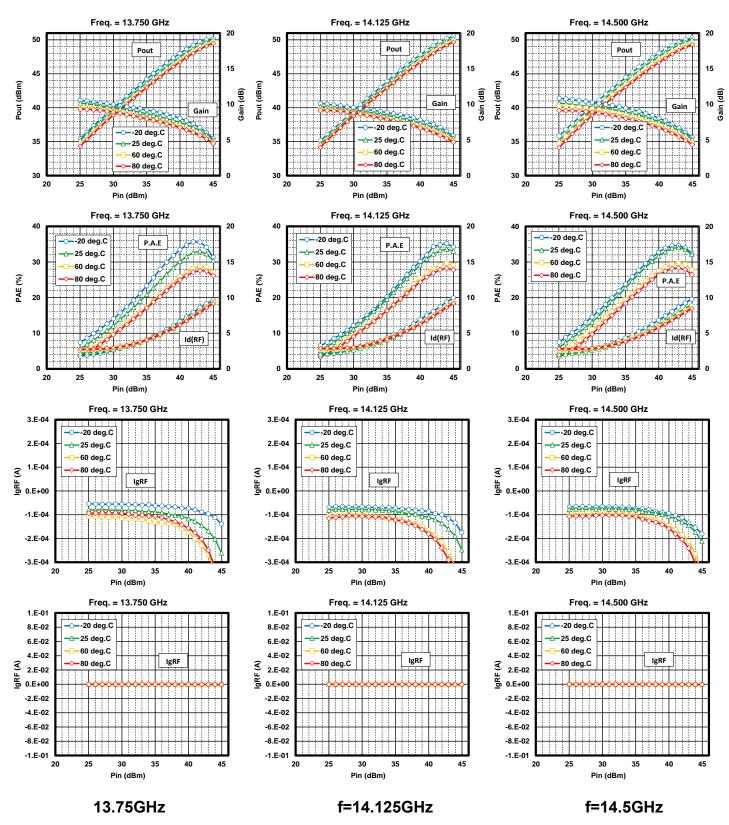


Fig.2 Pin vs Pout / Gain / PAE / IDRF / IGRF

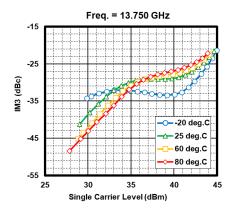
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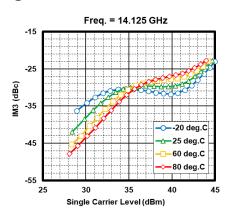
### MGFK50G3745

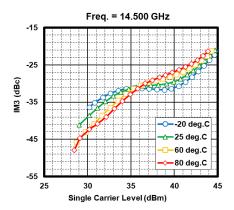
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# 3. TWO-TONE Characteristics VDS=24V, Idq=2.4A, Rg=10Ω, Δf=5MHz







f=13.75GHz

f=14.125GHz

f=14.5GHz

Fig.3 Pout vs IM3

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